

L Number	Hits	Search Text	DB	Time stamp
1	2	5,175,613.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/31 14:09
2	1	gasket and 5,175,613.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/31 14:10
3	4	(lossy with gasket) and (esd (electrostatic with (discharge pulse)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/31 14:43
4	2813297	microprocessor chip die ic (integrated adj circuit) semiconductor microchip	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/31 14:42
5	21	(lossy with gasket)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/31 14:44
6	21	(gasket with lossy)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/31 14:44
7	27	(gasket same lossy)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/31 14:44
8	10	(microprocessor chip die ic (integrated adj circuit) semiconductor microchip) and ((gasket same lossy))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/31 14:48
9	2	5,717,577.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/31 14:59
10	2	5,717,577.pn. and ((gasket same lossy))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/31 14:59
11	39	(esd (electrostatic with (discharge pulse))) and ((lossy esd (electrostatic with (discharge pulse))) with gasket)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/31 15:50

L Number	Hits	Search Text	DB	Time stamp
1	6	heat and (esd (electrostatic with (discharge pulse))) and ((lossy esd (electrostatic with (discharge pulse))) with gasket)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/10/31 12:27